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AUTOMATED DISPENSE FOR SPIN COATING APPLICATIONS

Powered by DataStream™
Technology

The Cee® suite of wafer processing equipment is a complete system for developing production quality processes in R&D, laboratory, or low-volume production environments.

PRODUCT OFFERINGS



DISPOSABLE SYRINGE

- R&D Applications
- Viscosities of 1 to 12,000cps
- Dispense volumes of 0.1ml to 50ml
- Pinch valve suck-back
- Available in 30ml and 55ml sizes



CARTRIDGE

- Production and R&D Applications
- Viscosities of 1 to 3,000cps
- Dispense volumes of 0.1ml to 100ml
- Integrated suck-back valve
- Adjustable & repeatable flow control
- 175ml to 945ml sizes available



PRESSURE CAN

- Production and R&D Applications
- Viscosities of 1 to 3,000cps*
- Dispense volumes of 0.1ml to 100ml**
- Integrated suck-back valve
- Adjustable & repeatable flow control
- 1, 2, 3, 5, 10-gallon sizes available

*1 to 10,000cps if gravity-fed

**1 to 100ml if gravity-fed

CONTACT US TODAY



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**THE LEADER IN HIGH PERFORMANCE
WAFER PROCESSING EQUIPMENT**